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REPLY UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP ART UNIT 1765

#10
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6/12/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Franz LAERMER et al.
Serial No. : 09/720,761
Filed : March 26, 2001
For : METHOD OF PLASMA ETCHING OF SILICON
Examiner : Kin Chan Chen
Art Unit : 1765
Confirmation No. : 5642

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Richard L. Mayer

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S I R:

This paper addresses the Final Office Action dated April 10, 2003 in connection with the above-captioned application.

REMARKS

I. Introduction

Claims 19 to 36 are pending in the present application. In view of the following remarks, it is respectfully submitted that all of the presently pending claims are allowable, and reconsideration is respectfully requested.

II. Rejection of Claims 19 to 22 and 24 to 27 Under 35 U.S.C. § 103(a)

Claims 19 to 22 and 24 to 27 were rejected under 35 U.S.C. § 103(a) as unpatentable over Journal of the Electrochemical Society, Dec. 1982, USA Bd 129, Nr. 12, Pages 2755 to 2760 ("Flamm et al."). Applicants respectfully submit that Flamm et al. do not render obvious claims 19 to 22 and 24 to 27 for the following reasons.